

STRESS-RELIEF LAYER AND STRESS-COMPENSATION COLLAR
IN CONTACT ARRAYS,
AND PROCESSES OF MAKING SAME

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ABSTRACT OF THE DISCLOSURE

A stress-relief layer is formed by dispensing a polymer upon a substrate lower surface under conditions to partially embed a solder bump that is disposed upon the lower surface. The stress-relief layer flows against the solder bump. A stress-compensation collar is formed on a board to which the substrate is mated and
10 the SCC partially embeds the solder bump. An article that exhibits a stress-relief layer and a stress-compensation collar is also included. A computing system that includes a stress-relief layer and a stress-compensation collar is also included.

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